

WHAT IS CLAIMED IS:

1. A semiconductor integrated device comprising:
a first semiconductor device having a plurality of terminals; and

5 a second semiconductor device having a plurality of terminals, wherein a few or all of the terminals of said first semiconductor device being connected with the corresponding terminals of said second semiconductor device; and

10 a substrate which holds said first and second semiconductor devices,

wherein the terminals of said first semiconductor device that are connected to the corresponding terminals of said second semiconductor device, or the terminals of
15 said second semiconductor device that are connected to the corresponding terminals of said second semiconductor device, or the terminals of said first and second semiconductor devices that are connected to each other are placed together.

20 2. The semiconductor integrated device according to claim 1, wherein terminals of said first and second semiconductor device that are connected to each other are arranged opposite to each other on said substrate.

3. The semiconductor integrated device according to claim 1, wherein the terminals of said first semiconductor device that are connected to the corresponding terminals of said second semiconductor device, or the terminals of said second semiconductor device that are connected to the corresponding terminals of said second semiconductor device, or the terminals of said first and second semiconductor devices that are connected to each other are arranged on one side of an edge part where the plurality of connecting terminals of said first semiconductor device or second semiconductor device are arranged.

4. The semiconductor integrated device according to claim 1, wherein the terminals of said first semiconductor device that are connected to the corresponding terminals of said second semiconductor device, or the terminals of said second semiconductor device that are connected to the corresponding terminals of said second semiconductor device, or the terminals of said first and second semiconductor devices that are connected to each other are arranged in series on one side of an edge section where the plurality of connecting terminals of said first semiconductor device or second semiconductor device are arranged and on a side adjacent to the one side.

5. The semiconductor integrated device according to claim 1, wherein the connecting terminals constituting said prescribed connecting terminal group are arranged in series such that these connecting terminals are related by the prescribed order to each other.

6. The semiconductor integrated device according to claim 1, wherein the respective pluralities of connecting terminals of said first semiconductor device and second semiconductor device are arranged on the long side part in the longitudinal direction, the respective short side parts of said first semiconductor device and second semiconductor device are arranged opposite to each other and said respective prescribed connecting terminals are arranged in series such that these groups are related with each other by the prescribed order from the short side part in the long side part close to said short side part.

7. The semiconductor integrated device according to claim 1, wherein said first semiconductor device comprises:

a power source input terminal which receives the supply of power source voltage from said second semiconductor device;

an oscillating unit connected to said power source input terminal;

a multiplying unit which changes the frequency of a signal which said oscillating unit oscillates; and

an output terminal which outputs the signal whose frequency is changed by said multiplying unit; and said

5 second semiconductor device comprises:

a power source output terminal which supplies power source voltage to said first semiconductor device; and

a signal input terminal which receives the signal from said output terminal.

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8. A semiconductor integrated device according to claim 7, wherein said first semiconductor device further comprises:

a power source voltage supplying unit which supplies
15 power source to said oscillating unit;

a power source switching unit which supplies the power source supplied from the power source voltage supplying unit to said oscillating unit and said multiplying unit when said power source voltage supplying unit supplies power source
20 and which supplies the power source supplied from said power source input terminal to said oscillating unit and said multiplying unit when said power source voltage supplying unit does not supply power source.

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9. A semiconductor integrated device comprising:

a first semiconductor device having a plurality of terminals; and

a second semiconductor device having a plurality of
5 terminals, wherein a few or all of the terminals of said first semiconductor device being connected with the corresponding terminals of said second semiconductor device; and

a substrate, having two sides, and holds said first
10 semiconductor device on one side and said second semiconductor device on the other side,

wherein the terminals of said first semiconductor device that are connected to the corresponding terminals of said second semiconductor device, or the terminals of
15 said second semiconductor device that are connected to the corresponding terminals of said second semiconductor device, or the terminals of said first and second semiconductor devices that are connected to each other are placed opposite to each, on the two sides of the substrate, with a through-hole
20 corresponding to each terminal in between.

10. The semiconductor integrated device according to claim 9, wherein the terminals of said first semiconductor device that are connected to the corresponding terminals of said
25 second semiconductor device, or the terminals of said second

semiconductor device that are connected to the corresponding terminals of said second semiconductor device, or the terminals of said first and second semiconductor devices that are connected to each other are arranged on one side of an edge part where the plurality of connecting terminals of said first semiconductor device or second semiconductor device are arranged.

11. The semiconductor integrated device according to claim 9, wherein the terminals of said first semiconductor device that are connected to the corresponding terminals of said second semiconductor device, or the terminals of said second semiconductor device that are connected to the corresponding terminals of said second semiconductor device, or the terminals of said first and second semiconductor devices that are connected to each other are arranged in series on one side of an edge section where the plurality of connecting terminals of said first semiconductor device or second semiconductor device are arranged and on a side adjacent to the one side.

12. The semiconductor integrated device according to claim 9, wherein the connecting terminals constituting said prescribed connecting terminal group are arranged in series such that these connecting terminals are related by the

prescribed order to each other.

13. The semiconductor integrated device according to claim
9, wherein the respective pluralities of connecting
5 terminals of said first semiconductor device and second
semiconductor device are arranged on the long side part in
the longitudinal direction, the respective short side parts
of said first semiconductor device and second semiconductor
device are arranged opposite to each other and said
10 respective prescribed connecting terminals are arranged in
series such that these groups are related with each other
by the prescribed order from the short side part in the long
side part close to said short side part.

15 14. The semiconductor integrated device according to claim
9, wherein said first semiconductor device comprises:

a power source input terminal which receives the supply
of power source voltage from said second semiconductor
device;

20 an oscillating unit connected to said power source
input terminal;

a multiplying unit which changes the frequency of a
signal which said oscillating unit oscillates; and

an output terminal which outputs the signal whose
25 frequency is changed by said multiplying unit; and said

second semiconductor device comprises:

a power source output terminal which supplies power source voltage to said first semiconductor device; and

a signal input terminal which receives the signal from
5 said output terminal.

15. A semiconductor integrated device according to claim 14, wherein said first semiconductor device further comprises:

10 a power source voltage supplying unit which supplies power source to said oscillating unit;

a power source switching unit which supplies the power source supplied from the power source voltage supplying unit to said oscillating unit and said multiplying unit when said
15 power source voltage supplying unit supplies power source and which supplies the power source supplied from said power source input terminal to said oscillating unit and said multiplying unit when said power source voltage supplying unit does not supply power source.

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